



# Sidewall Spacer NVM Characterization and Modeling



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# Agenda

- Introduction
- Bit Cell Testing
- Early Results
- Second Testchip
- Testing Sources
- NVM Modeling
- Conclusions

## Introduction

# Radiation Hard Non-Volatile Memory Design

### Objective:

The objective is understanding how the novel Sidewall Spacer Memory Bit Cell (SwSpc) is affected by Total Ionizing radiation Dose (TID) and design a full radiation tolerant memory IP.

### Main tasks:

- Characterization of Bit Cell tolerance to TID
- Physics Based Model development of the Bit Cell

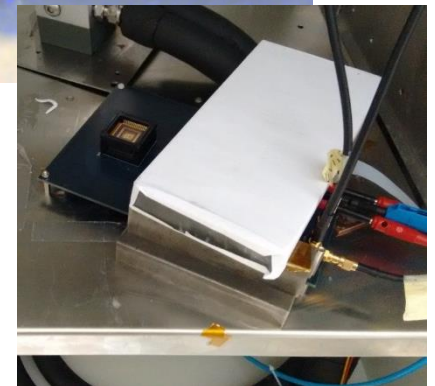
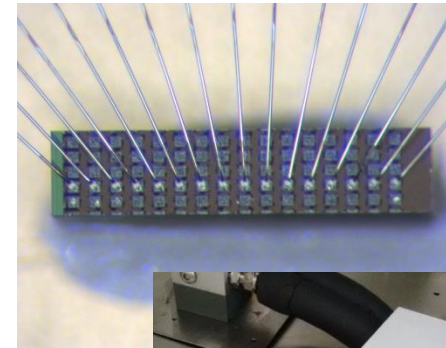
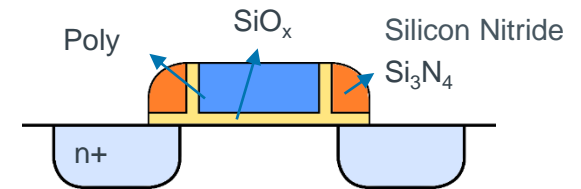
### Contract duration:

July 2016 – December 2018 (30M)

### Next steps:

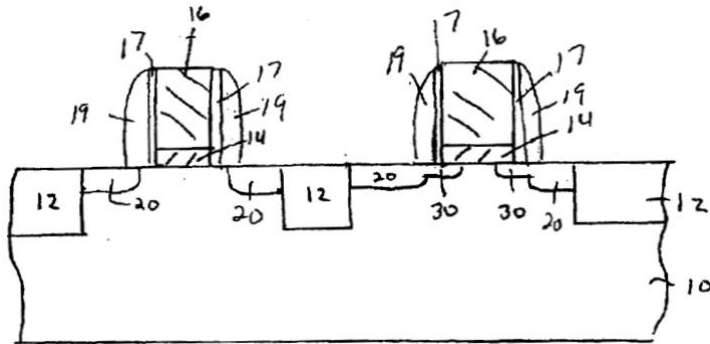
Collaboration with NSCore (Fukuoka, JP) on the development of a full Memory IP

February 2018 – April 2018



# Introduction

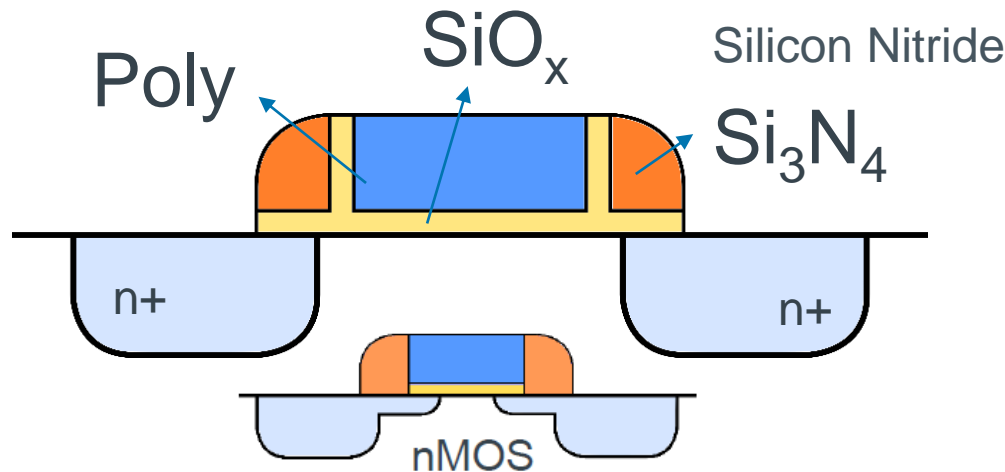
## US 6,518,614 B1



### EMBEDDED ONE-TIME PROGRAMMABLE NON-VOLATILE MEMORY USING PROMPT SHIFT DEVICE

Inventors: **Matthew J. Breitwisch**, Essex Junction, VT (US); **Bomy A. Chen**, Ridgefield, CT (US); **Chung H. Lam**, Williston, VT (US)

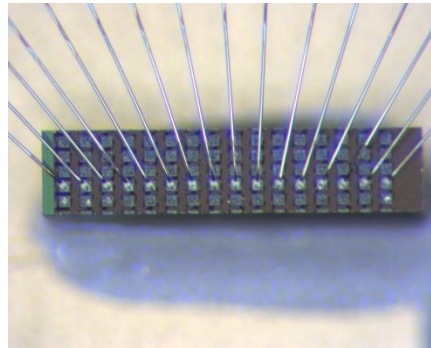
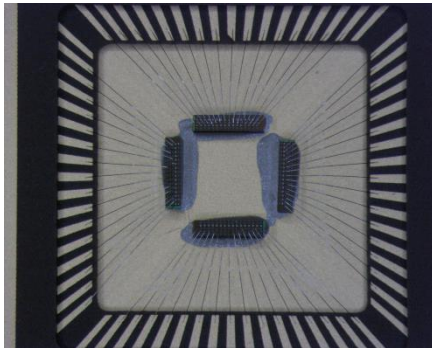
Assignee: **International Business Machines Corporation**, Armonk, NY (US)



The patent can be used for bit cell development in multiple technologies due to ams/IBM patent license agreement

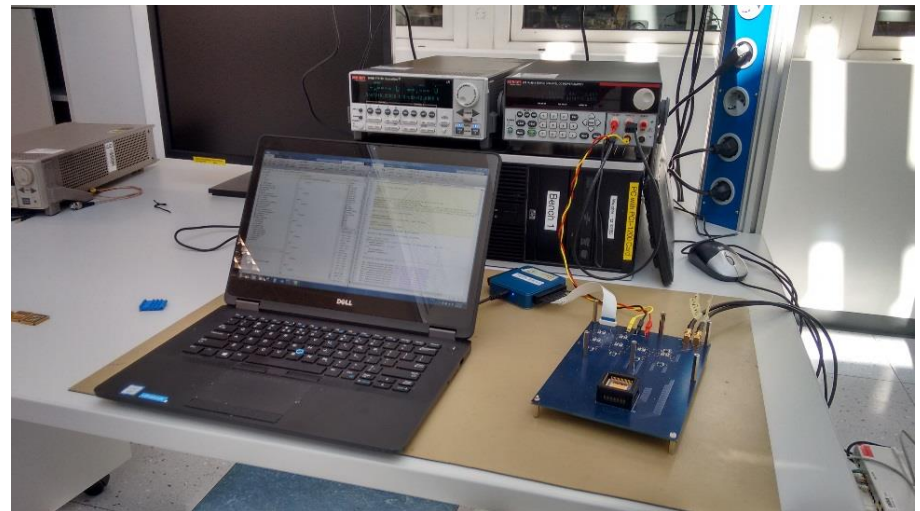


# BitCell Testing

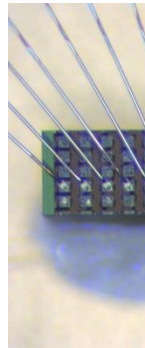
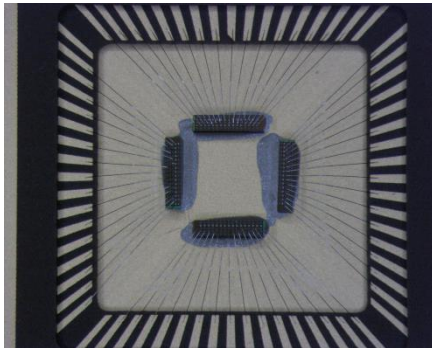


Arrays are available and have been tested electrically.

The radiation test setup measurement agrees with on-wafer measurements.

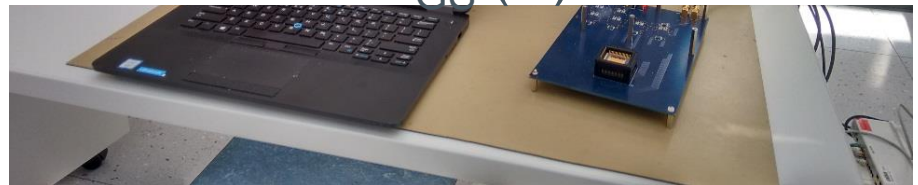
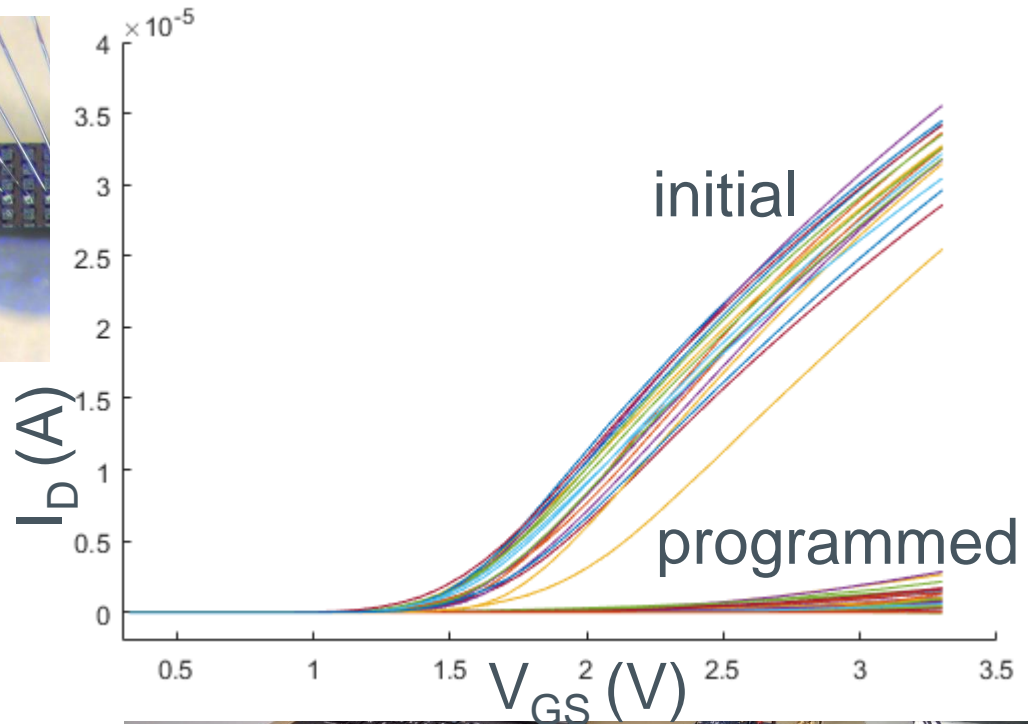


# BitCell Testing



Arrays are available and have been tested electrically.

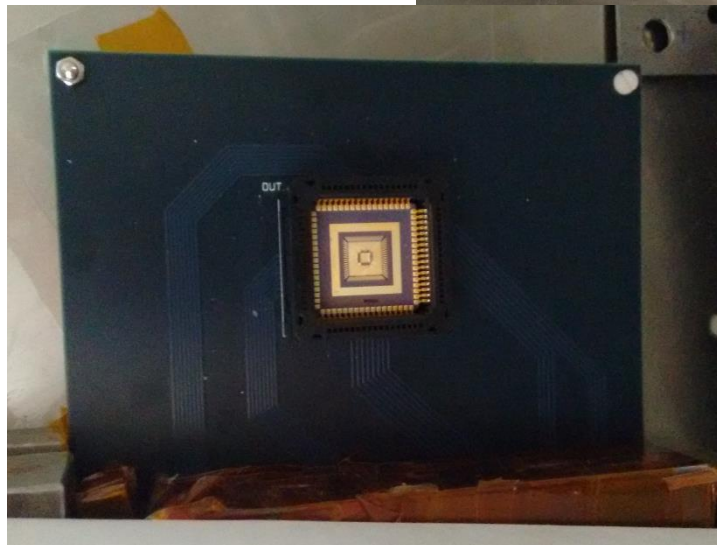
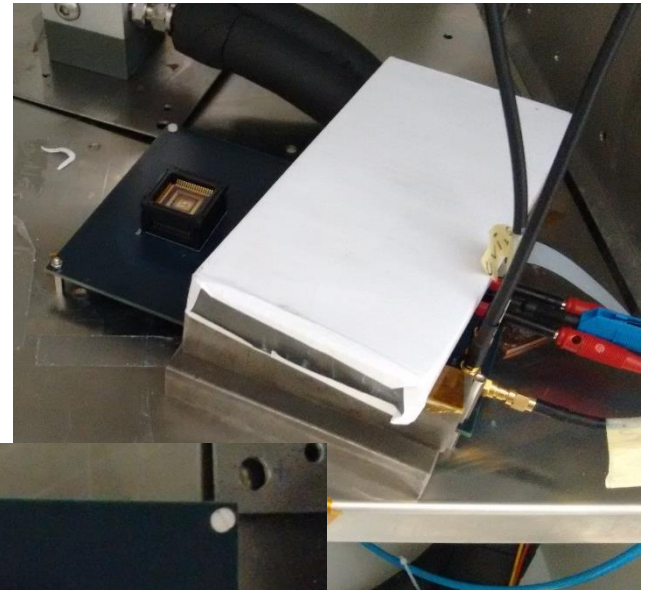
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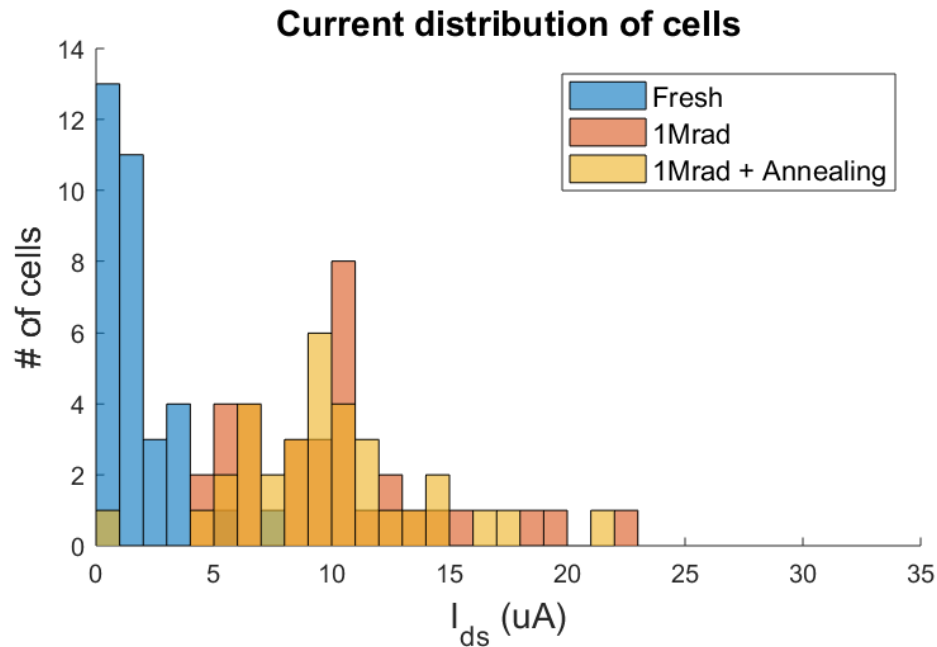
# BitCell Testing



60 keV wide angle calibrated X-ray source



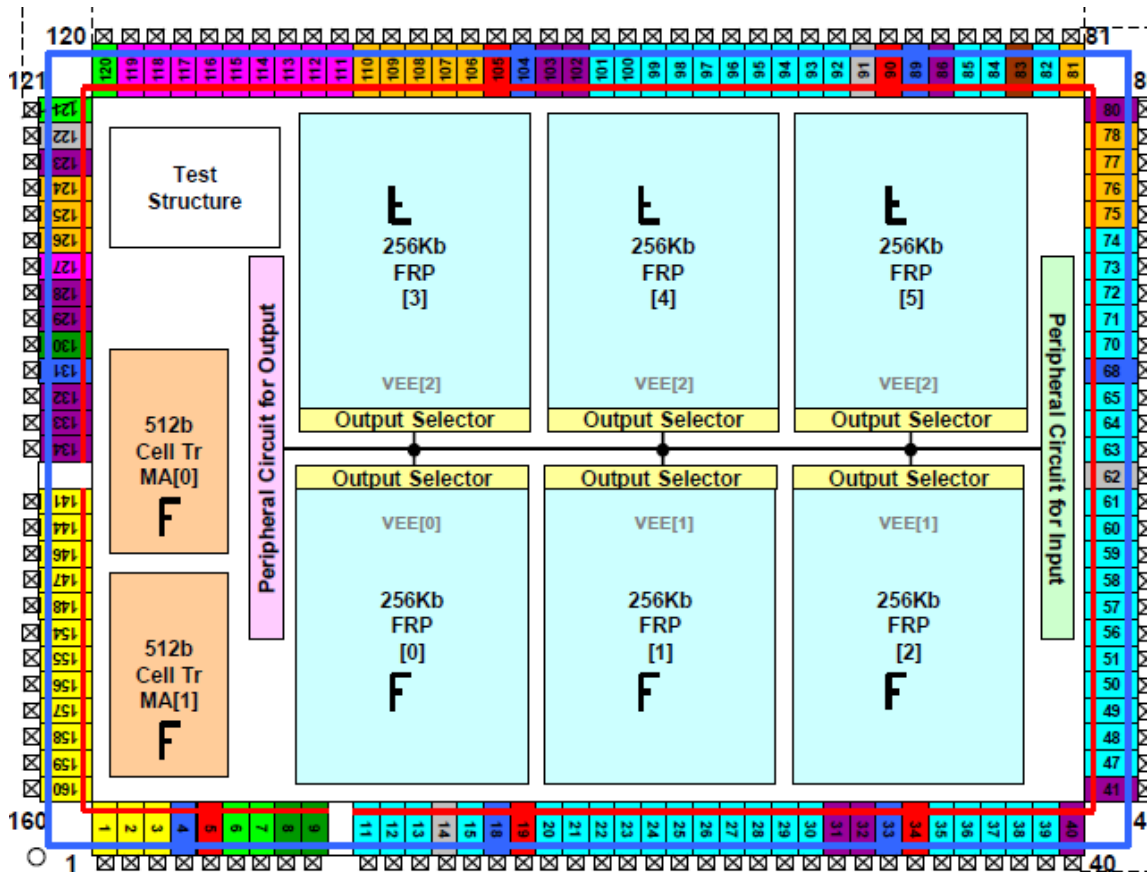
# Early Results



- Variation of MUX paths within  $\pm 5\%$
- Array structure prevented single cell analysis
- Defects and testing mishandling caused a poor statistical sample pool.



# Second Testchip



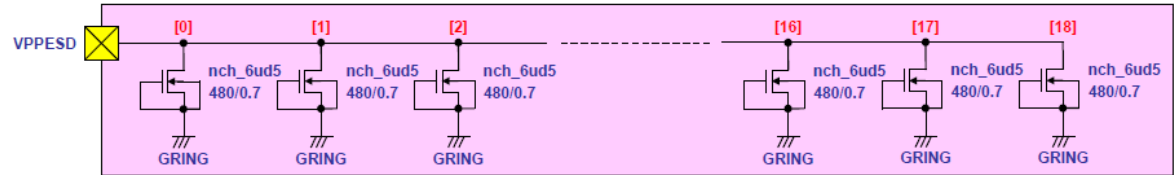
## Result of the Secondment in Japan

Collection of Macro with different types of device.

Bit Cell Matrices for distribution analyses  
Single Structures for device characterization

# Second Testchip

✓ For VPP



✓ DNW=VRING

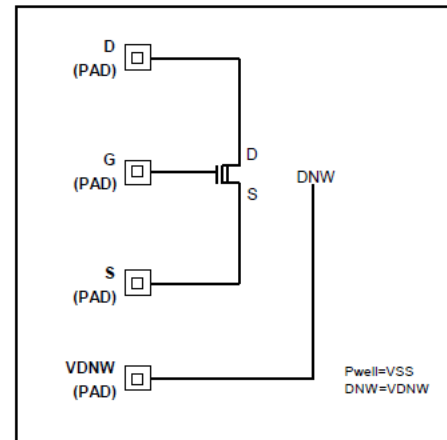
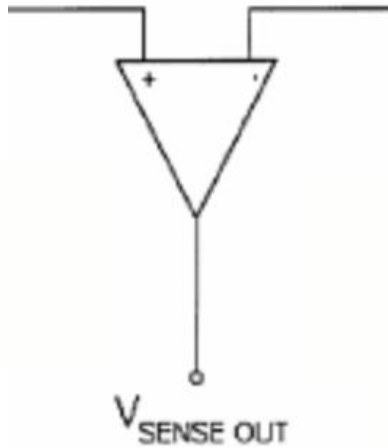
## ESD Protection

✓ For VEE



✓ DNW=GRING

## Sense Amplifier



## Bit Cell

## Testing Sources



### Test sources:

- X-ray sources
- $\gamma$ -ray sources

TID based on trapped energy in matter:

=> Geometry related (secondary effects in X-ray surface absorption)

## Testing Sources

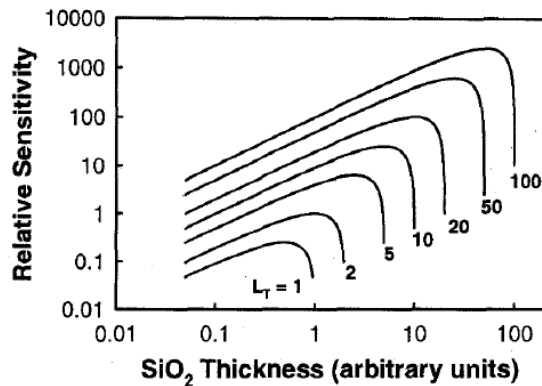
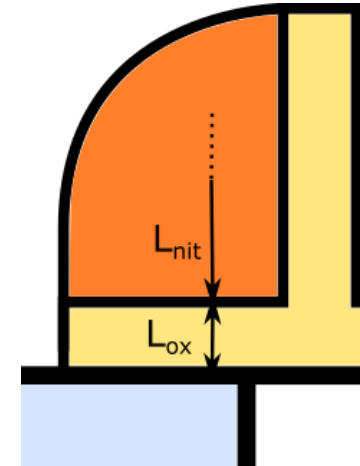
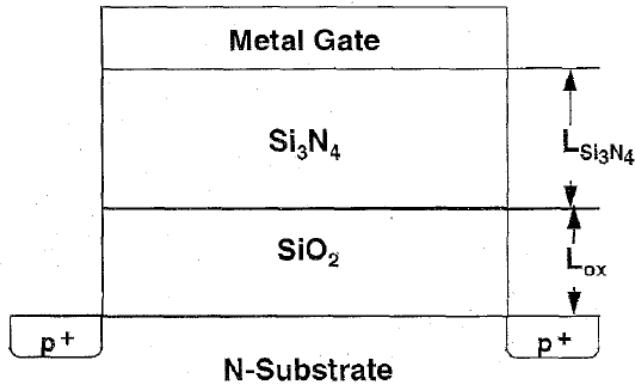


Collaboration between Federico Faccio at CERN and TUGraz:

- Comparison of the method used at CERN (AXUVHS5 Opto Diode Corp) with the standard method using vacuum chamber.
- Investigation of the difference between X-ray and  $\gamma$ -ray use in testing circuits.



# NVM Modeling



- Determination of the sensitivity of the device depending on material thickness
- Possible correction factors due to geometry improvements to the device compared to state of the art devices

J. R. Schwank, S. B. Roeske, D. E. Beutler, D. J. Moreno and M. R. Shaneyfelt, "A dose rate independent pMOS dosimeter for space applications," in *IEEE Transactions on Nuclear Science*, vol. 43, no. 6, pp. 2671-2678, Dec. 1996.

## Conclusions & Future Work

- SwSpc Memory Bit Cell remains a good candidate in terms of radiation tolerance
- More investigations are needed for poor results
- The new testchip provides all the necessary structures for a consistent measurement
- More investigation is necessary on testing techniques because of possible lack of consistency in TID definition
- A physical model is needed to understand fully the potential of the BitCell



**Thank you**

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# Structure of the Cell Transistor Matrix

✓ Bit Cell

